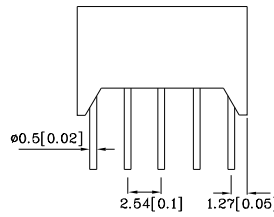
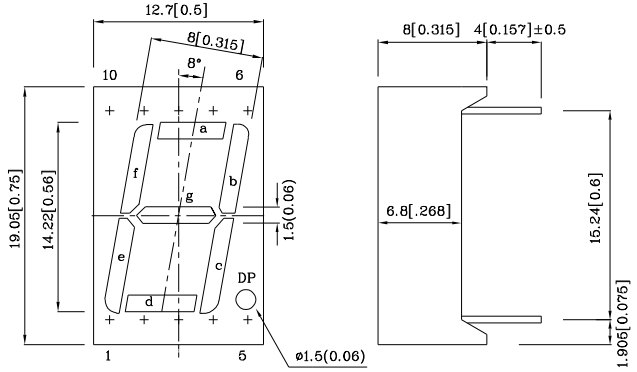
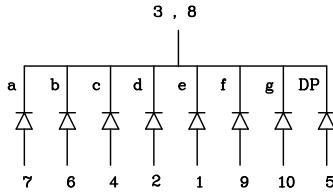


**PRELIMINARY SPEC**

**Features**

- 0.56 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, WHITE SEGMENT.
- RoHS COMPLIANT.



**ATTENTION**  
 OBSERVE PRECAUTIONS  
 FOR HANDLING  
 ELECTROSTATIC  
 DISCHARGE  
 SENSITIVE  
 DEVICES

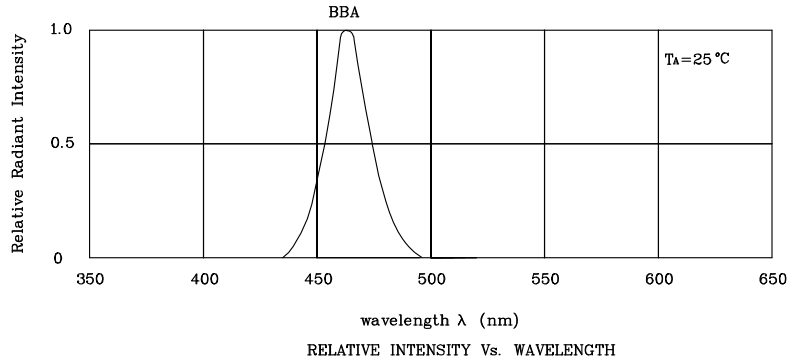
**Notes:**

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
3. Specifications are subject to change without notice.

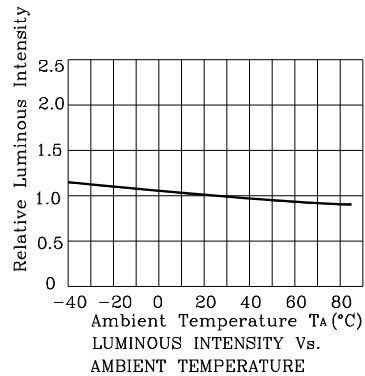
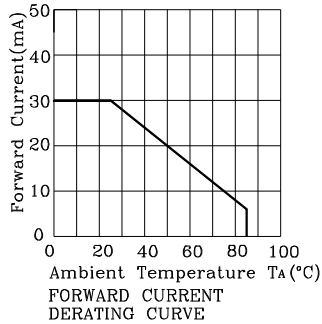
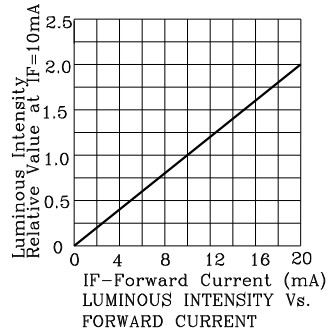
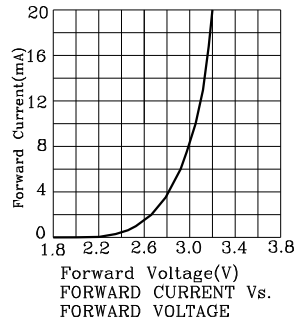
Absolute Maximum Ratings (TA=25°C)		BBA (InGaN)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	100	mA
Power Dissipation	P <sub>T</sub>	120	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V
Lead Solder Temperature [2mm Below Package Base]	260°C For 3~5 Seconds		

Operating Characteristics (TA=25°C)		BBA (InGaN)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	3.05	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	4.0	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength Of Peak Emis- sion (Typ.) (I <sub>F</sub> =10mA)	λ P	468	nm
Wavelength Of Dominant Emission (Typ.) (I <sub>F</sub> =10mA)	λ D	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	Δλ	21	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	100	pF

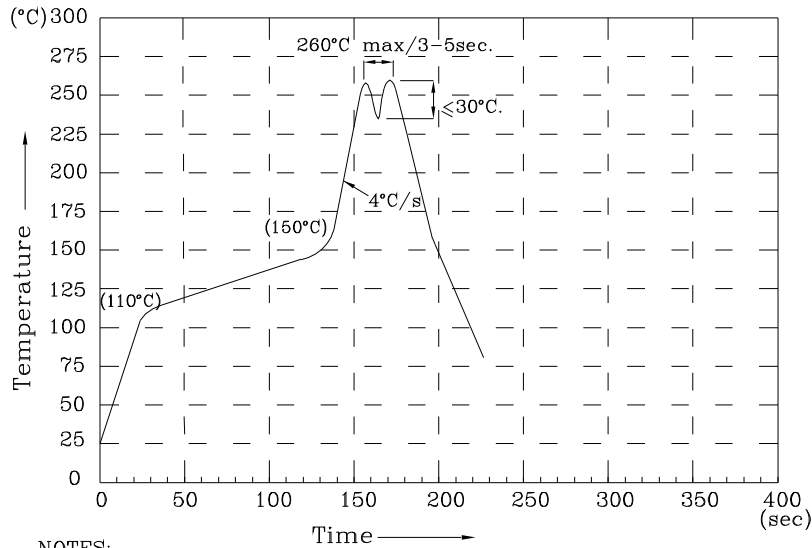
Part Number	Emitting Color	Emitting Material	Luminous Intensity (I <sub>F</sub> =10mA)		Wavelength nm λ P	Description
			min.	typ.		
DBBA14C	Blue	InGaN	1900	10290	468	Common Cathode, Rt. Hand Decimal



❖ **BBA**



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

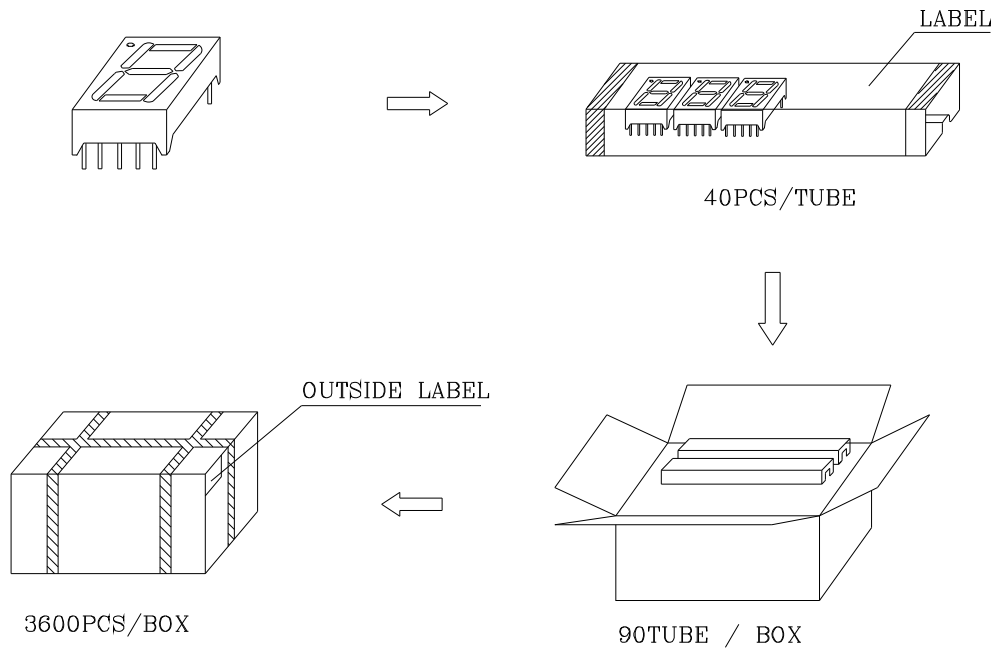
the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

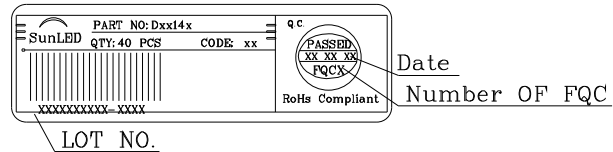
Note: Accuracy may depend on the sorting parameters.

**PACKING & LABEL SPECIFICATIONS**

**DBBA14C**



Inside LABEL Paste On The IC-tube



Outside LABEL Paste On The Box

